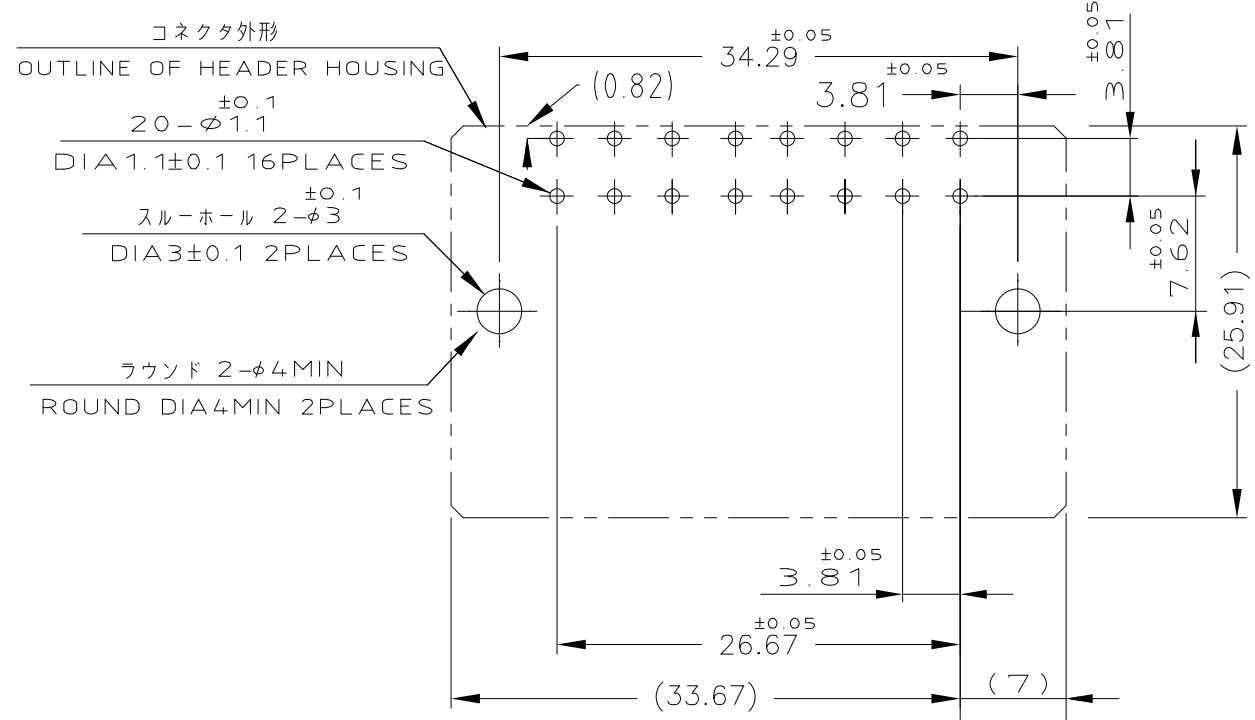
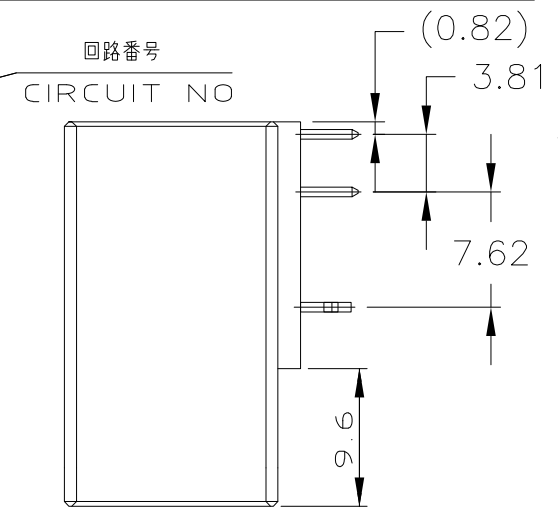
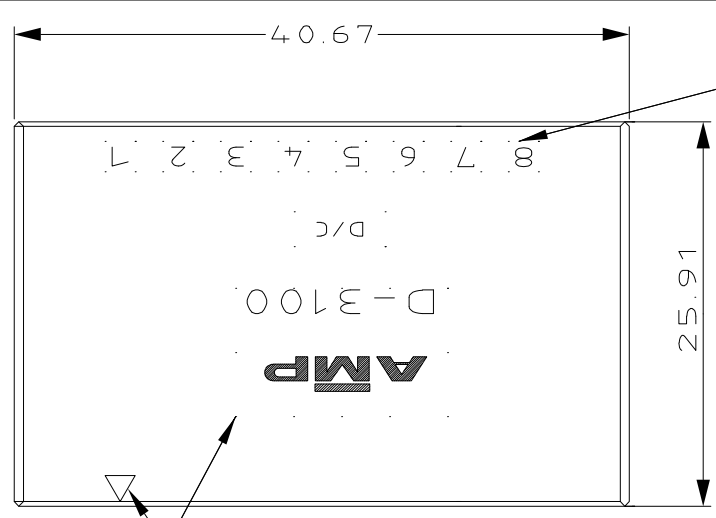


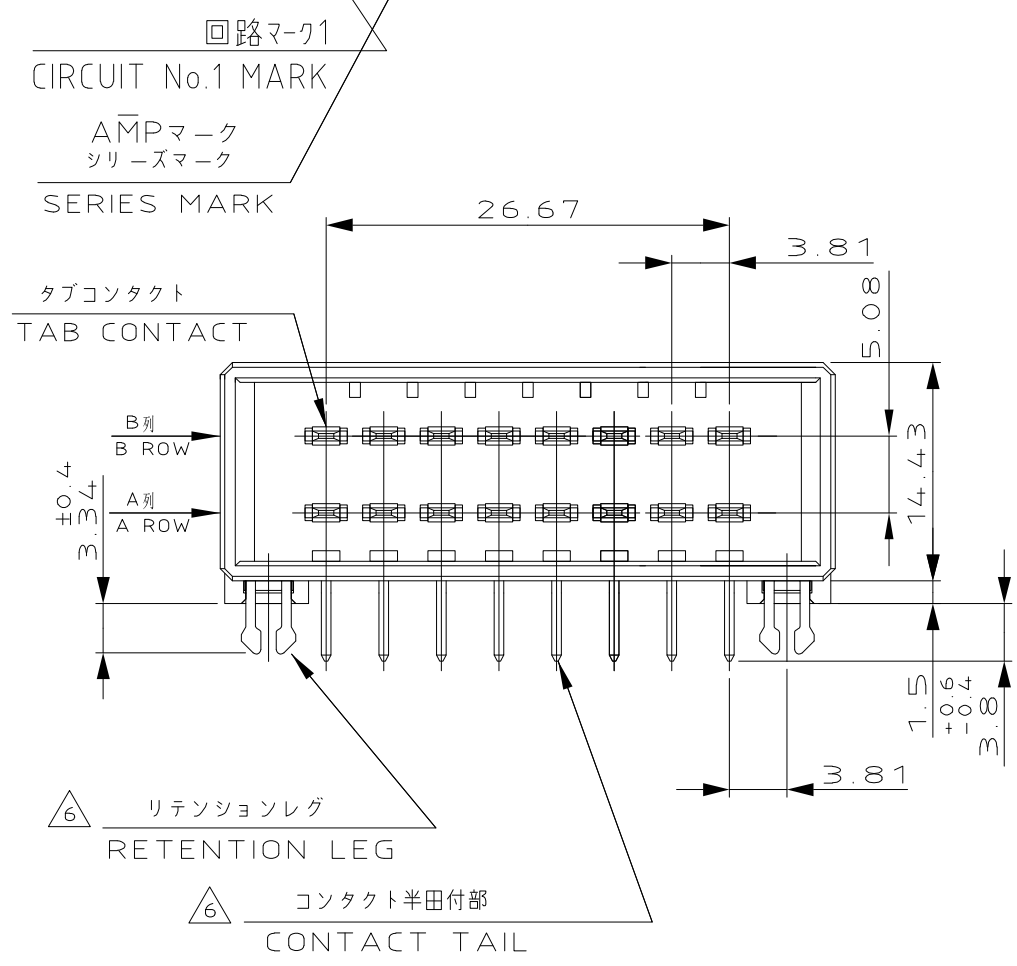
THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION
 © COPYRIGHT - Tyco Electronics JAPAN G.K. ALL RIGHTS RESERVED.

LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	D		REVISED	14JAN2015	K.K	N.Y



推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1 (非累積公差) (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1 (NOT ACCUMULATE TOLERANCE) (CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER COLOR: BLACK
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
- GENERAL TOLERANCE
 10 ≥ : ±0.3
 30 ≥ > 10 : ±0.4
 100 ≥ > 30 : ±0.45
 ANGLE : ±3°

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 色: 黒
 コンタクト: 銅合金
 リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
 接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき
- 一般公差
 10 ≥ : ±0.3
 30 ≥ > 10 : ±0.4
 100 ≥ > 30 : ±0.45
 角度 : ±3°

△6 △4	178307-5
△6 △3	178307-3
△6 △2	178307-2
(FINISH)	製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN K.IKEDA 16.MAR.95	TE Connectivity	
		CHK S.Manabe 23.MAR.95		
DIMENSIONS: mm		APVD K.Ikeda 13.MAR.95	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC 108-5453	16 POS DOUBLE ROW HORIZONTAL HDR ASSY FOR DYNAMIC 3100	
MATERIAL SEE NOTE		APPLICATION SPEC 114-5206	SIZE	CAGE CODE
FINISH SEE NOTE		WEIGHT -	DRAWING NO A3 00779 C-178307	
		CUSTOMER DRAWING		RESTRICTED TO -
		SCALE 2:1	SHEET 1 OF 1	REV D